

L Number	Hits	Search Text	DB	Time stamp
-	19031	(cmp or polish or polishing or planarize or planarizing) and test	USPAT	2003/09/24 11:24
-	1653	(cmp or polish or polishing or planarize or planarizing).ab. and test	USPAT	2003/09/12 15:38
-	205	((cmp or polish or polishing or planarize or planarizing).ab. and test) and (trench or STI)	USPAT	2003/09/12 15:39
-	1	((((cmp or polish or polishing or planarize or planarizing).ab. and test) and (trench or STI)) and (reclaim or reclaiming)	USPAT	2003/09/12 15:39
-	193	((((cmp or polish or polishing or planarize or planarizing).ab. and test) and (trench or STI)) and semiconductor	USPAT	2003/09/12 15:42
-	189	(((((cmp or polish or polishing or planarize or planarizing).ab. and test) and (trench or STI)) and semiconductor) and @ay<=2001	USPAT	2003/09/15 11:31
-	3681	(cmp or polish or polishing or planarize or planarizing).ab. and pattern	USPAT	2003/09/15 15:07
-	1169	((cmp or polish or polishing or planarize or planarizing).ab. and pattern) and (trench or STI)	USPAT	2003/09/15 11:36
-	922	((((cmp or polish or polishing or planarize or planarizing).ab. and pattern) and (trench or STI)) and ((silicon adj oxide) or SiO or SiO?sub.2 or (silicon adj dioxide))	USPAT	2003/09/15 15:25
-	127	(((((cmp or polish or polishing or planarize or planarizing).ab. and pattern) and (trench or STI)) and ((silicon adj oxide) or SiO or SiO?sub.2 or (silicon adj dioxide))) and sacrificial	USPAT	2003/09/15 11:58
-	1992	((cmp or polish or polishing or planarize or planarizing).ab. and pattern) and ((silicon adj oxide) or SiO or SiO?sub.2 or (silicon adj dioxide))	USPAT	2003/09/15 11:58
-	196	((((cmp or polish or polishing or planarize or planarizing).ab. and pattern) and ((silicon adj oxide) or SiO or SiO?sub.2 or (silicon adj dioxide))) and sacrificial	USPAT	2003/09/15 12:02
-	178	(((((cmp or polish or polishing or planarize or planarizing).ab. and pattern) and ((silicon adj oxide) or SiO or SiO?sub.2 or (silicon adj dioxide))) and sacrificial) and @ay<=2000	USPAT	2003/09/15 12:02
-	18	((cmp or polish or polishing or planarize or planarizing).ab. and pattern) and (reclaim or reclaimed or reclamation)	USPAT	2003/09/15 13:31
-	498	(cmp or polish or polishing or planarize or planarizing) and (reclaim or reclaiming or reclaimed or reclamation)	USPAT	2003/09/15 13:33
-	88	((cmp or polish or polishing or planarize or planarizing) and (reclaim or reclaiming or reclaimed or reclamation)) and ((silicon adj oxide) or SiO or SiO?sub.2 or (silicon adj dioxide))	USPAT	2003/09/15 13:39
-	81	((((cmp or polish or polishing or planarize or planarizing) and (reclaim or reclaiming or reclaimed or reclamation)) and ((silicon adj oxide) or SiO or SiO?sub.2 or (silicon adj dioxide))) and @ay<=2000	USPAT	2003/09/15 13:39
-	86	(cmp or polish or polishing or planarize or planarizing).ab. and (test with pattern)	USPAT	2003/09/15 13:54

-	85	((cmp or polish or polishing or planarize or planarizing).ab. and (test with pattern)) not (((cmp or polish or polishing or planarize or planarizing) and (reclaim or reclaiming or reclaimed or reclamation)) and ((silicon adj oxide) or SiO or SiO?sub.2 or (silicon adj dioxide))) and @ay<=2000)	USPAT	2003/09/15 13:54
-	74	((cmp or polish or polishing or planarize or planarizing).ab. and (test with pattern)) not (((cmp or polish or polishing or planarize or planarizing) and (reclaim or reclaiming or reclaimed or reclamation)) and ((silicon adj oxide) or SiO or SiO?sub.2 or (silicon adj dioxide))) and @ay<=2000) and @ay<=2000	USPAT	2003/09/15 14:03
-	6	Lacy-Michael-S.in.	USPAT	2003/09/15 14:03
-	56	("3753269" "4318250" "4510113" "4576612" "4672985" "4720939" "4728552" "4753838" "4841680" "4927432" "4934102" "4954141" "4962562" "5020283" "5081051" "5104421" "5177908" "5197999" "5212910" "5234867" "5257478" "5287663" "5329734" "5335453" "5433651" "5484323" "5487697" "5489233" "5531635" "5534106" "5536202" "5547417" "5558568" "5575707" "5578362" "5593344" "5605760" "5611943" "5622526" "5643044" "5655951" "5692947" "5692950" "5725417" "5759918" "5762536" "5779526" "5810964" "5871390" "5897426" "5899798" "5908530" "5958794" "6093651" "6106351" "6206759").PN.	USPAT	2003/09/15 14:48
-	2821	(cmp or polish or polishing or planarize or planarizing) and sacrificial	USPAT	2003/09/15 15:07
-	1700	((cmp or polish or polishing or planarize or planarizing) and sacrificial) and ((strip or stripping or remove or removing or etch or etching) with sacrificial)	USPAT	2003/09/15 15:09
-	402	((cmp or polish or polishing or planarize or planarizing) and sacrificial) and ((strip or stripping or remove or removing or etch or etching) with (sacrificial near oxide))	USPAT	2003/09/15 15:10
-	345	((cmp or polish or polishing or planarize or planarizing) and sacrificial) and ((strip or stripping or remove or removing or etch or etching) with (sacrificial near oxide))) and @ay<=2000	USPAT	2003/09/15 15:11
-	22	((cmp or polish or polishing or planarize or planarizing) and sacrificial) and ((strip or stripping or remove or removing or etch or etching) with (sacrificial near oxide))) and @ay<=2000) and (test or testing)	USPAT	2003/09/15 15:10
-	182	((cmp or polish or polishing or planarize or planarizing) and sacrificial) and ((strip or stripping or remove or removing or etch or etching) with (sacrificial near oxide))) and @ay<=2000) and ((trench or STI) same sacrificial)	USPAT	2003/09/15 15:24
-	664	(re\$claim or re\$claiming or re\$claimed or reclamation) and semiconductor	USPAT	2003/09/15 15:25

-	157	((re\$1claim or re\$1claiming or re\$1claimed or reclamation) and semiconductor) and ((silicon adj oxide) or SiO or SiO?sub.2 or (silicon adj dioxide) or sacrificial)	USPAT	2003/09/15 15:26
-	147	((re\$1claim or re\$1claiming or re\$1claimed or reclamation) and semiconductor) and ((silicon adj oxide) or SiO or SiO?sub.2 or (silicon adj dioxide) or sacrificial)) and @ay<=2000	USPAT	2003/09/15 15:26
-	499	(CMP or polishing or polish or planarize or planarizing) and (reclaim or reclaiming or reclaimed or reclamation)	USPAT	2003/09/16 16:32
-	472	((CMP or polishing or polish or planarize or planarizing) and (reclaim or reclaiming or reclaimed or reclamation)) and @ay<=2000	USPAT	2003/09/16 16:33
-	111	((CMP or polishing or polish or planarize or planarizing) and (reclaim or reclaiming or reclaimed or reclamation)) and @ay<=2000) and semiconductor	USPAT	2003/09/16 16:34
-	7	("3923567" "4738056" "5051375" "5131979" "5622875" "5855735" "5981301").PN.	USPAT	2003/09/16 16:34
-	121	(reclaim or reclaiming or reclaimed or reclamation) and (trench or STI)	USPAT	2003/09/20 10:41
-	20	5622875.URPN.	USPAT	2003/09/20 10:46
-	7	("3923567" "4738056" "5051375" "5131979" "5622875" "5855735" "5981301").PN.	USPAT	2003/09/20 10:47
-	11	5131979.URPN.	USPAT	2003/09/20 10:48
-	921	(cmp or polish or polishing or planarize or planarizing) and (test near3 (pattern or structure))	USPAT	2003/09/24 11:30
-	591	((cmp or polish or polishing or planarize or planarizing) and (test near3 (pattern or structure))) and (oxide or dioxide or SiO or SiO?sub.2)	USPAT	2003/09/24 11:27
-	591	((cmp or polish or polishing or planarize or planarizing) and (test near3 (pattern or structure))) and (oxide or dioxide or SiO or SiO?sub.2)) and (cmp or polish or polishing or planarize or planarizing or planarization)	USPAT	2003/09/24 11:29
-	517	((((cmp or polish or polishing or planarize or planarizing) and (test near3 (pattern or structure))) and (oxide or dioxide or SiO or SiO?sub.2)) and (cmp or polish or polishing or planarize or planarizing or planarization)) and (silicon or semiconductor)	USPAT	2003/09/24 11:29
-	87	(((((cmp or polish or polishing or planarize or planarizing) and (test near3 (pattern or structure))) and (oxide or dioxide or SiO or SiO?sub.2)) and (cmp or polish or polishing or planarize or planarizing or planarization)) and (silicon or semiconductor)) and ((cmp or polish or polishing or planarize or planarizing) same(test near3 (pattern or structure)))	USPAT	2003/09/24 13:17
-	15	("5278105" "5386088" "5652465" "5665633" "5747380" "5885856" "5923563" "5948573" "5956618" "5970238" "6087733" "6232161" "6281049" "6448630" "6486066").PN.	USPAT	2003/09/24 11:31
-	6	("5736427" "6136709" "6214716" "6274483" "6297156" "6306737").PN.	USPAT	2003/09/24 11:41

-	3821	(sacrifice or sacrificial) with (oxide or dioxide or SiO or SiO?sub.2)	USPAT	2003/09/24 13:19
-	3043	((sacrifice or sacrificial) with (oxide or dioxide or SiO or SiO?sub.2)) and semiconductor	USPAT	2003/09/24 13:19
-	8	((sacrifice or sacrificial) with (oxide or dioxide or SiO or SiO?sub.2)) and (re\$1claim or re\$1claiming or re\$1claimed or re\$1claimation)	USPAT	2003/09/24 13:20
-	144	(re\$1claim or re\$1claiming or re\$1claimed or re\$1claimation) near4 (substrate or wafer)	USPAT	2003/09/24 13:21
-	134	((re\$1claim or re\$1claiming or re\$1claimed or re\$1claimation) near4 (substrate or wafer)) and @ay<=2000	USPAT	2003/09/24 15:06
-	1	6451696.pn.	USPAT	2003/09/24 15:24
-	4	("3715842" "3923567" "5622875" "5855735").PN.	USPAT	2003/09/24 15:07
-	237523	transistor	USPAT	2003/09/24 15:24
-	168	transistor and (reclaim or reclaiming)	USPAT	2003/09/24 15:24